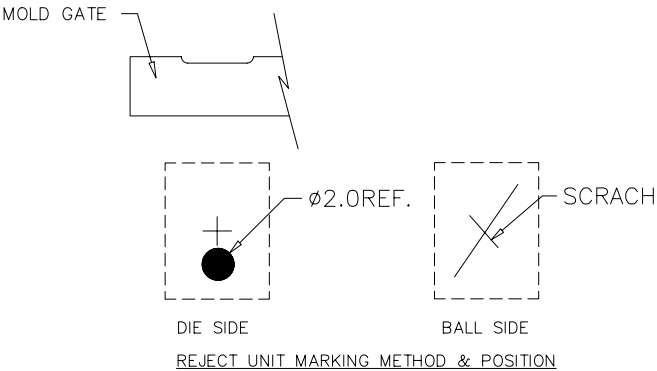
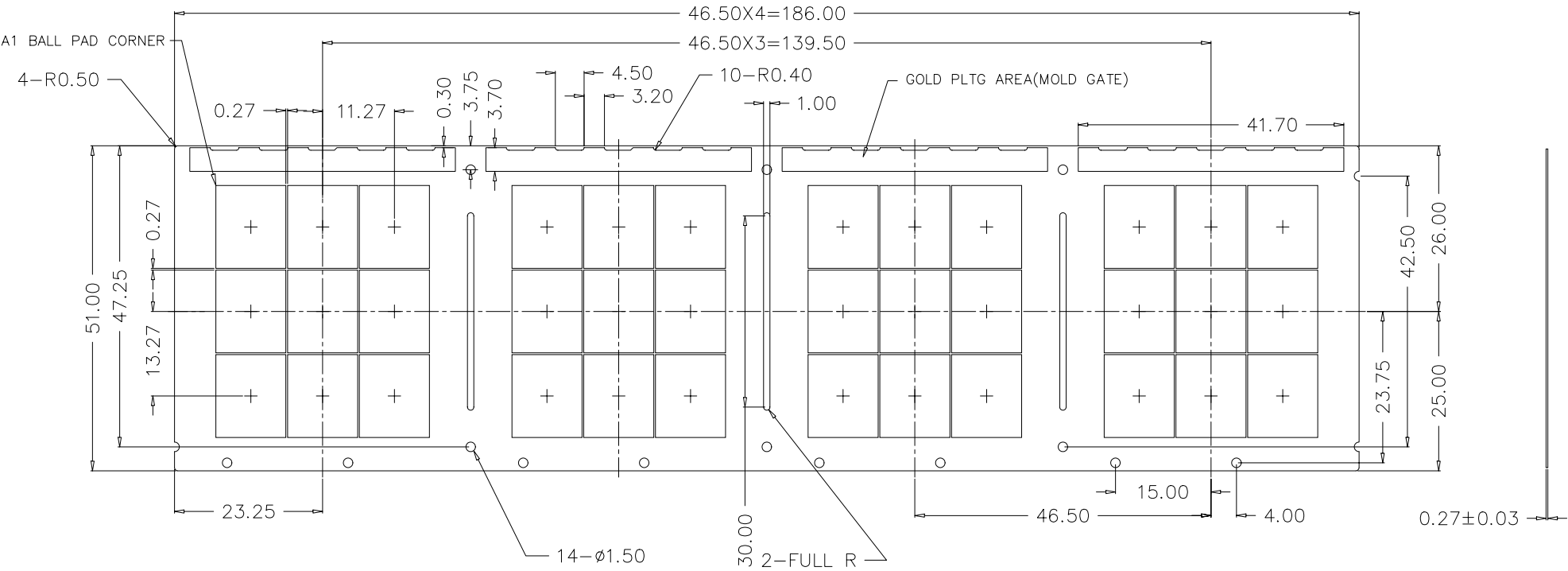


REV.	DESCRIPTION	DATE	ENG	APPROVAL
-	GENERATION		MJ BAIK	
1	CHANGE FULL CIRCUIT DESIGN		MJ BAIK	



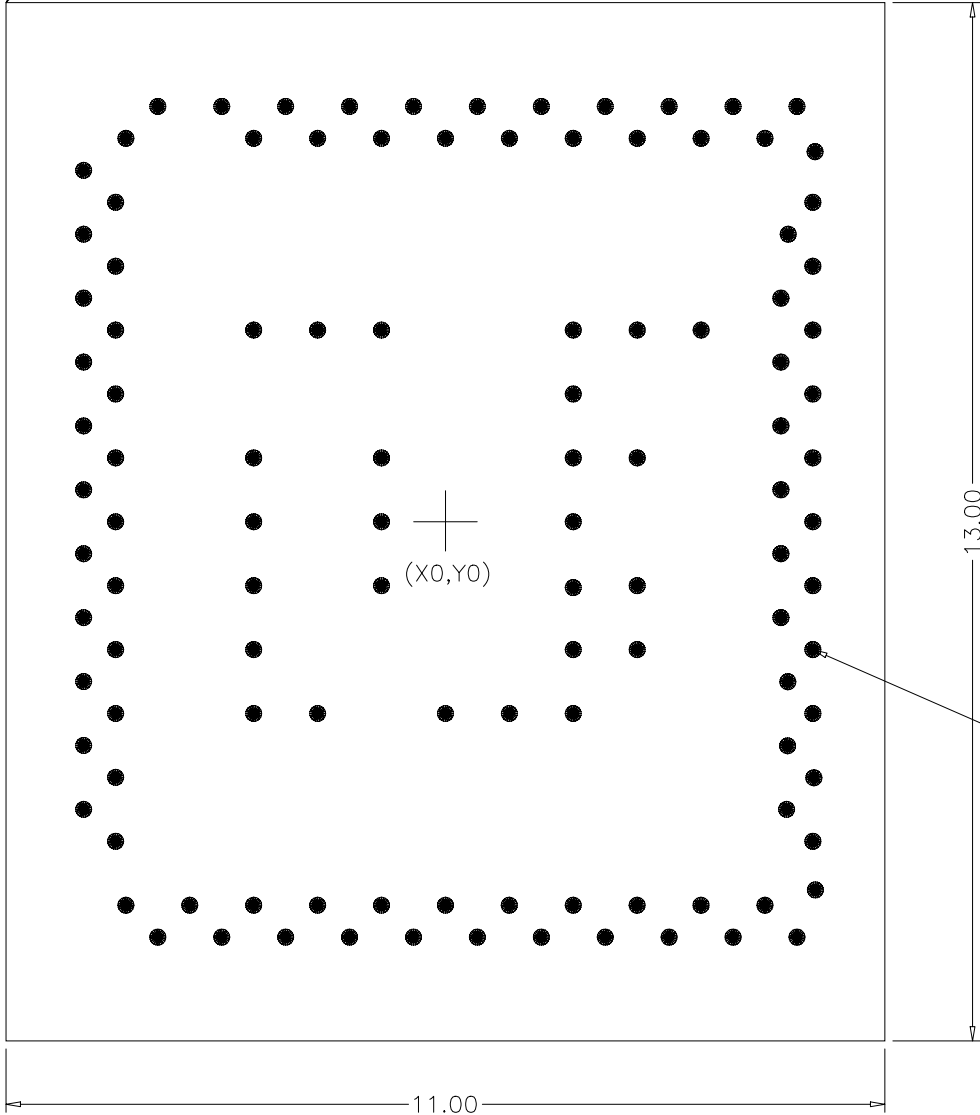
UNLESS SPECIFIED OTHERWISE	
LAMINATE CORE	BT CCL-HL832HS, 0.15MM±0.01MM
SOLDER MASK	TAIYO PSR4000-AUS5, MIN15UM ON METAL
LAMINATE COPPER	12±5UM
PLATING	COPPER 15UM+15UM/-0.0UM IN VIA HOLE
	NICKEL 5UM~15UM
	GOLD 0.5UM~1.0UM

DIMENSIONAL UNIT: MM	DATE: 08/23/01	DRAWN: MJ BAIK	TITLE: FBGA 11.0X13.0MM 100 BALL 0.80MM BALL PITCH, 2 LAYER 3X3 MATRIX 36UNITS WIDE SUBSTRATE DESIGN	
SCALE: 1:1	UNTOLERANCED DIMENSIONS	ENGINEER: MJ BAIK		
PROJECTION UNLESS SPECIFIED		CHECKED: DS SEO		
INCH MILLIMETER XX : N/A .X : ±0.1 XXX : ±0.001 .XX : ±0.05 XXXX : N/A .XXX : ±0.03 ANGLE : ±1°		APPROVED: -	CAD FILE: EEV-FLB11131	DRAWING NUMBER: EEV-FLB11131
Signetics Korea			REV: 1	SHEET: 1 OF 6

STRIP LAYOUT
PKG TOP VIEW

REV.	DESCRIPTION	DATE	ENG	APPROVAL
-	GENERATION		MJ BAIK	
1	CHANGE FULL CIRCUIT DESIGN		MJ BAIK	

A1 BALL PAD CORNER



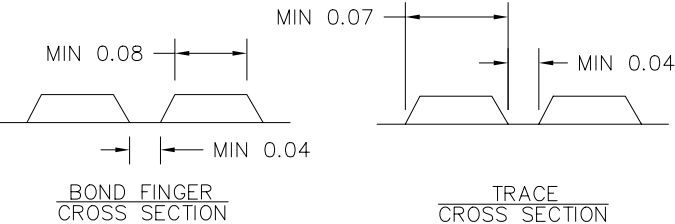
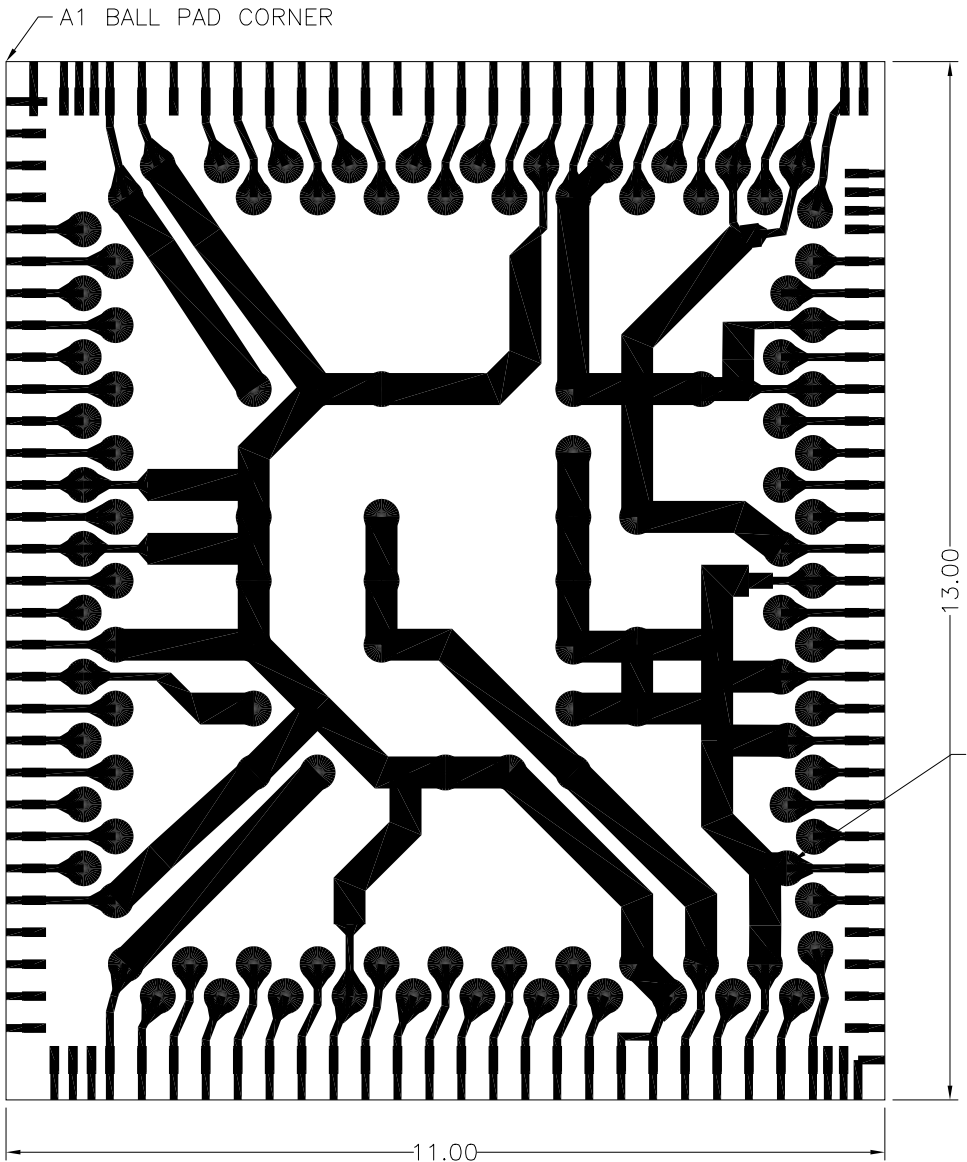
PTH DRILL DIA:114-Ø0.20

UNIT TOOLING DRAWING
PKG TOP VIEW

DIMENSIONAL UNIT: MM	DATE: 08/23/01	DRAWN: MJ BAIK	TITLE: FBGA 11.0X13.0MM 100 BALL 0.80MM BALL PITCH, 2 LAYER 3X3 MATRIX 36UNITS WIDE SUBSTRATE DESIGN	
SCALE: 10:1	UNTOLERANCED DIMENSIONS	ENGINEER: MJ BAIK		
PROJECTION UNLESS SPECIFIED	INCH MILLIMETER :N/A :N/A :±0.001 :±0.05 :N/A :±0.03 ANGLE : ±1°	CHECKED: DS SEO APPROVED: -		
CAD FILE: EEV-FLB11131		DRAWING NUMBER: EEV-FLB11131	REV: 1	SHEET: 2 OF 6

Signetics Korea

REV.	DESCRIPTION	DATE	ENG	APPROVAL
-	GENERATION		MJ BAIK	
1	CHANGE FULL CIRCUIT DESIGN		MJ BAIK	

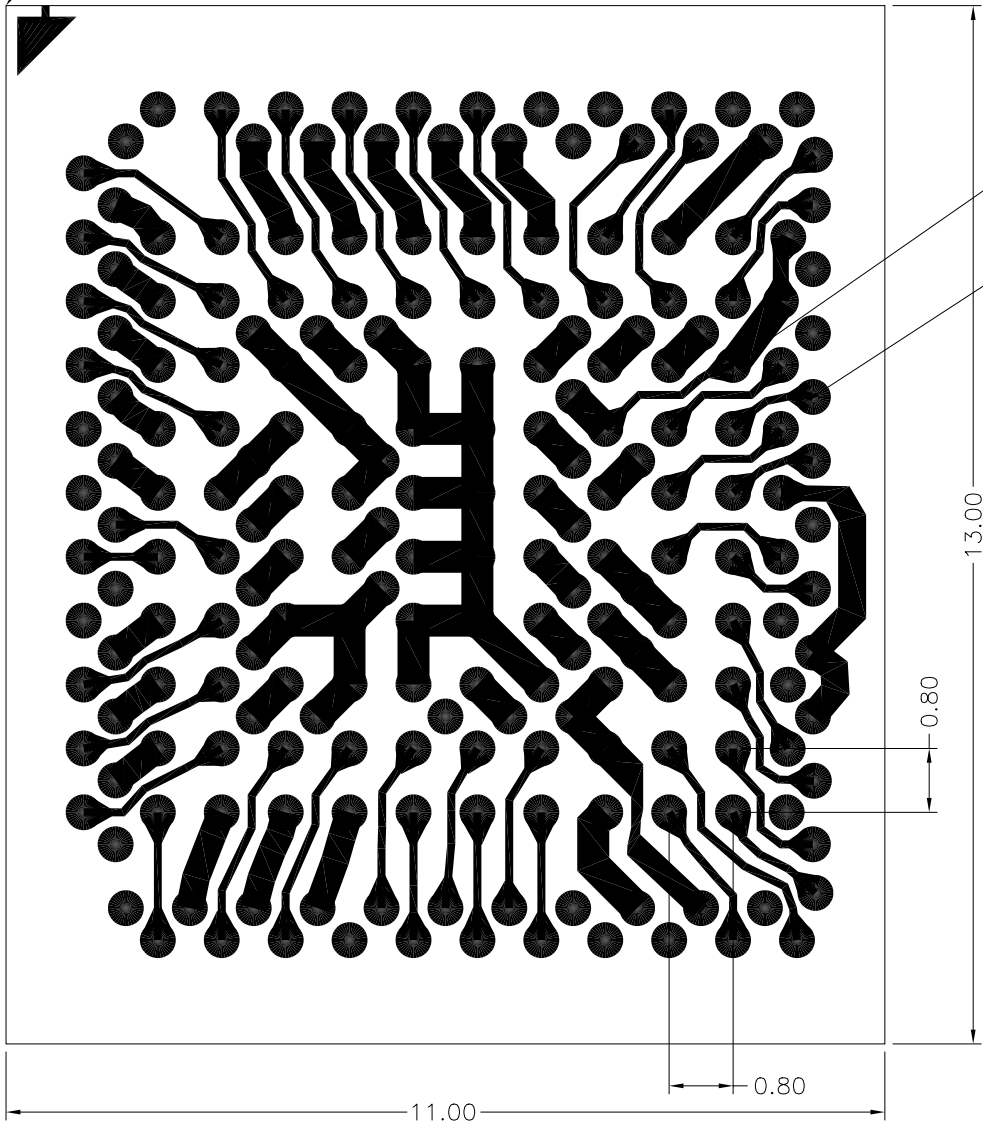


PATTERN LAYER 1 — TOP
PKG TOP VIEW

DIMENSIONAL UNIT:	MM	DATE:	08/23/01	DRAWN:	MJ BAIK	TITLE: FBGA 11.0X13.0MM 100 BALL 0.80MM BALL PITCH, 2 LAYER 3X3 MATRIX 36UNITS WIDE SUBSTRATE DESIGN			
SCALE:	10:1	UNTOLERANCED DIMENSIONS		ENGINEER:	MJ BAIK				
PROJECTION		INCH	MILLIMETER	CHECKED:	DS SEO				
UNLESS SPECIFIED		.XX :N/A .XXX :±0.001 .XXXX :N/A	.X :±0.1 .XX :±0.05 .XXX :±0.03	APPROVED:	-				
ANGLE : ±1°				CAD FILE:	EEV-FLB11131	DRAWING NUMBER:	EEV-FLB11131	REV.	SHEET:
Signetics Korea								1	4 OF 6

REV.	DESCRIPTION	DATE	ENG	APPROVAL
-	GENERATION		MJ BAIK	
1	CHANGE FULL CIRCUIT DESIGN		MJ BAIK	

A1 BALL PAD CORNER



BALL PAD DIA:Ø0.45

VIA PAD DIA:Ø0.45

13.00

0.80

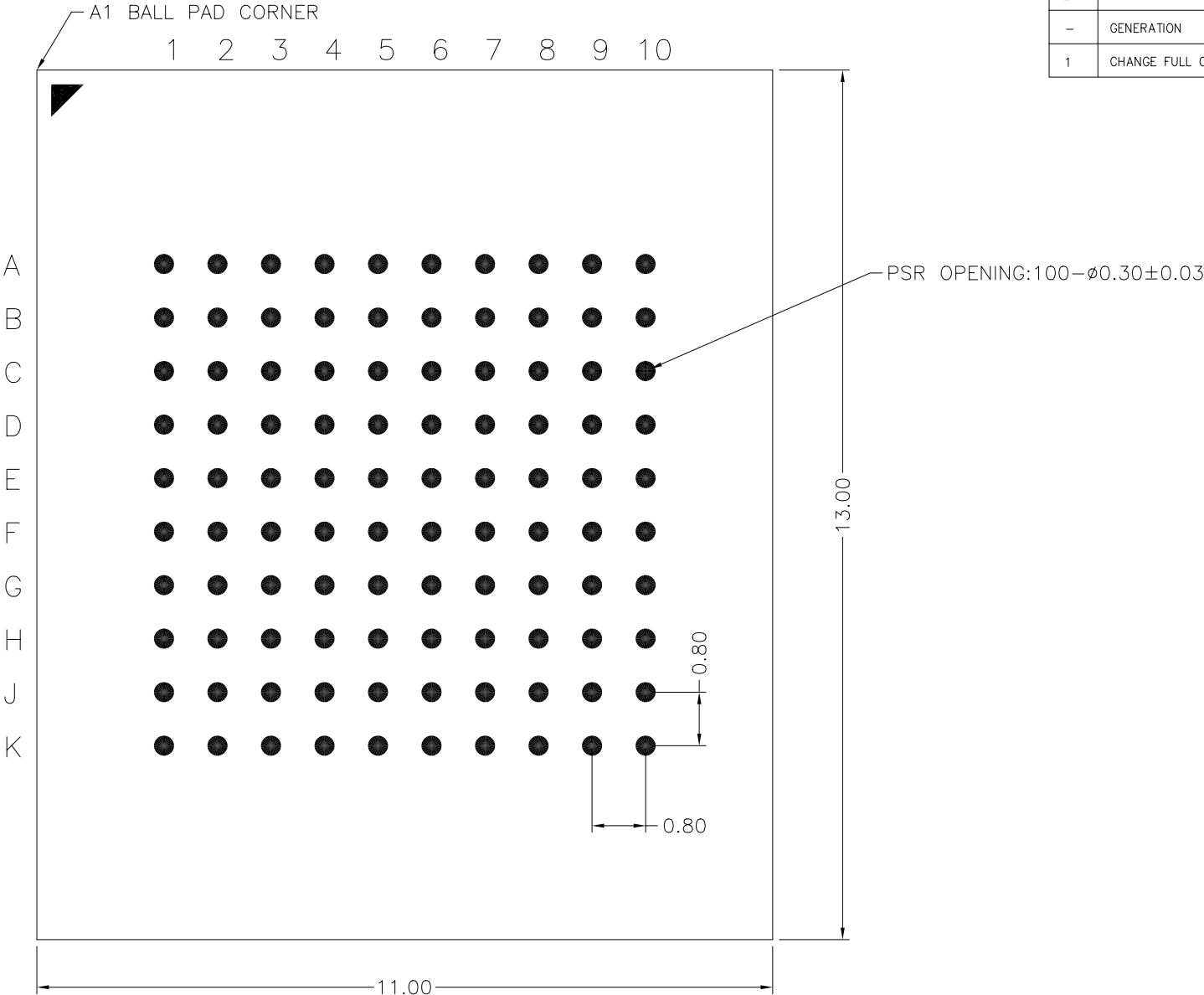
0.80

11.00

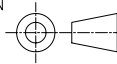
PATTERN LAYER 2 - BOTTOM
PKG TOP VIEW

DIMENSIONAL UNIT:	MM	DATE:	08/23/01	DRAWN:	MJ BAIK	TITLE: FBGA 11.0X13.0MM 100 BALL 0.80MM BALL PITCH, 2 LAYER 3X3 MATRIX 36UNITS WIDE SUBSTRATE DESIGN		
SCALE:	10:1	UNTOLERANCED DIMENSIONS		ENGINEER:	MJ BAIK			
PROJECTION		INCH	MILLIMETER	CHECKED:	DS SEO			
UNLESS SPECIFIED		.XX : N/A .XXX : ±0.001 .XXXX : N/A	.X : ±0.1 .XX : ±0.05 .XXX : ±0.03	APPROVED:	-			
				CAD FILE:		DRAWING NUMBER:	REV.	SHEET:
Signetics Korea				EEV-FLB11131		EEV-FLB11131	1	5 OF 6

REV.	DESCRIPTION	DATE	ENG	APPROVAL
-	GENERATION		MJ BAIK	
1	CHANGE FULL CIRCUIT DESIGN		MJ BAIK	



SOLDER MASK LAYER 2 - BOTTOM
PKG TOP VIEW

DIMENSIONAL UNIT: MM	DATE: 08/23/01	DRAWN: MJ BAIK	TITLE: FBGA 11.0X13.0MM 100 BALL 0.80MM BALL PITCH, 2 LAYER 3X3 MATRIX 36UNITS WIDE SUBSTRATE DESIGN										
SCALE: 10:1	UNTOLERANCED DIMENSIONS	ENGINEER: MJ BAIK											
PROJECTION UNLESS SPECIFIED		CHECKED: DS SEO											
	<table><tr><th>INCH</th><th>MILLIMETER</th></tr><tr><td>.XX : N/A</td><td>.X : ±0.1</td></tr><tr><td>.XXX : ±0.001</td><td>.XX : ±0.05</td></tr><tr><td>.XXXX : N/A</td><td>.XXX : ±0.03</td></tr></table>	INCH	MILLIMETER	.XX : N/A	.X : ±0.1	.XXX : ±0.001	.XX : ±0.05	.XXXX : N/A	.XXX : ±0.03	APPROVED: -			
INCH	MILLIMETER												
.XX : N/A	.X : ±0.1												
.XXX : ±0.001	.XX : ±0.05												
.XXXX : N/A	.XXX : ±0.03												
ANGLE : ±1°		CAD FILE: EEV-FLB11131	DRAWING NUMBER: EEV-FLB11131	REV. 1	SHEET: 6 OF 6								

Signetics Korea